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(21) International Application Number: PCT/US96/06202 (22) International Filing Date: 2 May 1996 (02.05.96) (30) Priority Data: 08/437,710 9 May 1995 (09.05.95) US (71) Applicant: THE DOW CHEMICAL COMPANY [US/US]; 2030 Dow Center, Abbott Road, Midland, MI 48640 (US). (72) Inventor: DALMAN, David, A.; 1907 Sylvan, Midland, MI 48640 (US). (74) Agent: COHN, Gary, C.; The Dow Chemical Company, Patent Dept., P.O. Box 1967, Midland, MI 48641-1967 (US).		(81) Designated States: CA, CN, JP, KR, MX, RU, <u>SG</u> /European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>
(54) Title: PRINTED WIRING BOARD(S) HAVING POLYIMIDEBENZOXAZOLE DIELECTRIC LAYER(S) AND THE MANUFACTURE THEREOF (57) Abstract A film of polyimidebenzoxazole (PIBO) having an electrically conductive layer adhered to at least one face thereto, wherein the PIBO film has a tensile strength greater than 200 MPa. A printed wiring board having at least one dielectric layer and at least one circuitry layer wherein at least one dielectric layer is a PIBO film. A printed wiring board (PWB) having at least one polyimidebenzoxazole (PIBO) dielectric layer wherein the PWB has at least one thin dielectric base material layer, at least one thin conductor, at least one narrow conductor width and at least one small diameter via.		